

RELIABILITY REPORT
FOR

DS1258W, 1Meg, 3Volt, SRAM Module

Dallas Semiconductor

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Prepared by:

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Conclusion:

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products and processes:

DS1258W, 1Meg, 3Volt, SRAM Module

In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at <http://www.maxim-ic.com/TechSupport/dsreliability.html>.*

Module Description:

A description of this Module can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l_datasheet3.cfm.*

Reliability Derating:

A module device consists of one or more IC's in a single, upward integrated, package. This package is assembled to include batteries, crystals, and other piece parts that make up the configuration of the Module. Because of either the complexity of the package or the included piece parts, standard high temperature reliability testing is not possible. Therefore, in order to determine the reliability of module products, the reliability of each of the piece parts is individually determined, then summed to determine the reliability of the integrated module product. If there are "n" significant components in the module then:

$$Fr(\text{module}) = Fr(1) + Fr(2) + Fr(3) + \dots + Fr(n)$$

Fr (module) = Failure rate of module
Fr(n) = Failure rate of the nth component

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

$$MTTF = 1/Fr$$

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this module/assembly is:

<u>Module Device:</u>	<u>Quantity:</u>	<u>MTTF (Yrs):</u>	<u>FITs:</u>
1 MEG SRAM 3V	2	3863	29.5
BR1632	2	23687	4.8
DS13D14	2	69619	1.6
Totals:		3170	36.0

The parameters used to calculate the module failure rate are as follows:

Cf: 60% **Ea: 0.7** **B: 0** **Tu: 25 °C** **Vu: 5.5 Volts**

The reliability data follows. At the start of this data is the module assembly information. This is a description of the module. The next section is the detailed reliability data for each stress found in the qualification / monitor. If there are additional processes or assemblies used as part of this report, a description of each will follow which includes the respective reliability data for that process/ assembly. The reliability data section includes the latest data available. Some of this data may be generic with other packages or products.

* Some proprietary products may be excepted from this requirement.

Assembly Information:

Assembly Site: Fastech
 Pin Count: 28
 Package Type: Module w/Hi Density SMT
 Body Size: 720
 Mold Compound: Amicon
 Lead Frame: PCB; FR4
 Lead Finsh:
 Die Attach: ?
 Bond Wire / Size: /
 Flammability: UL 94-V0
 Moisture Sensitivity (JEDEC J-STD20A)
 Date Code Range: 0033 to 0404

PACKAGE TESTS

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
SOLDERABILITY	0033	MIL-STD-883-2003	5 DYS	3	0
PHYSICAL DIMENSIONS	0033	MIL-STD-883-2016	5 DYS	6	0
SOLDERABILITY	0104	MIL-STD-883-2003	5 DYS	3	0
PHYSICAL DIMENSIONS	0104	MIL-STD-883-2016	5 DYS	6	0
SOLDERABILITY	0317	JESD22-B102	5 DYS	3	0
PHYSICAL DIMENSIONS	0317	JESD22-B100	5 DYS	6	0
SOLDERABILITY	0333	JESD22-B102	5 DYS	3	0
PHYSICAL DIMENSIONS	0333	JESD22-B100	5 DYS	6	0
SOLDERABILITY	0404	JESD22-B102	5 DYS	3	0
PHYSICAL DIMENSIONS	0404	JESD22-B100	5 DYS	6	0
Total:					0

STORAGE LIFE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
STORAGE LIFE	0033	70 C	1000 HRS	77	0
STORAGE LIFE	0104	70 C	1000 HRS	77	0
STORAGE LIFE	0317	70 C	1000 HRS	77	0
STORAGE LIFE	0333	70 C	1000 HRS	77	0
STORAGE LIFE	0404	70 C	1000 HRS	77	0
Total:					0

TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
TEMP CYCLE	0033	0C TO 70C	1000 CYS	77	1
TEMP CYCLE	0104	0C TO 70C	1000 CYS	77	0
TEMP CYCLE	0317	0C TO 70C	1000 CYS	77	0
TEMP CYCLE	0333	0C TO 70C	1000 CYS	77	0
TEMP CYCLE	0404	0C TO 70C	1000 CYS	77	0
Total:					1

UNBIASED MOISTURE RESISTANCE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
MOISTURE SOAK	0033	60C/90% R.H.	960 HRS	77	1
MOISTURE SOAK	0317	60C/90% R.H.	1000 HRS	77	0
MOISTURE SOAK	0333	60C/90% R.H.	1000 HRS	77	0
MOISTURE SOAK	0404	60C/90% R.H.	1000 HRS	77	0
Total:					1

Assembly Information:

Assembly Site: Fastech
Pin Count: 32
Package Type: Module w/Hi Density SMT
Body Size: 720
Mold Compound: Amicon
Lead Frame: PCB; FR4
Lead Finsh:
Die Attach: ?
Bond Wire / Size: /
Flammability: UL 94-V0
Moisture Sensitivity
(JEDEC J-STD20A)
Date Code Range: 9932 to 0139

PACKAGE TESTS

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
SOLDERABILITY	9932	MIL-STD-883-2012 : TOP & SIDE VIEW	5 DYS	3	0
X-RAY	9932	MIL-STD-883-2012 : TOP & SIDE VIEW	5 DYS	6	0
SOLDERABILITY	9951	MIL-STD-883-2012 : TOP & SIDE VIEW	5 DYS	3	0
X-RAY	9951	MIL-STD-883-2012 : TOP & SIDE VIEW	5 DYS	6	0
Total:					0

STORAGE LIFE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
STORAGE LIFE	0139	85 C	1000 HRS	49	0
Total:					0

TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
TEMP CYCLE	9932	-40 TO 85C	1000 CYS	77	1
TEMP CYCLE	9951	-40 TO 85C	1000 CYS	77	0
TEMP CYCLE	0139	-40 TO 85C	1000 CYS	50	0
Total:					1

UNBIASED MOISTURE RESISTANCE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
MOISTURE SOAK	9951	60C/90% R.H.	960 HRS	77	1
MOISTURE SOAK	0006	60C/90% R.H.	960 HRS	77	1
MOISTURE SOAK	0039	60C/90% R.H.	576 HRS	77	0
MOISTURE SOAK	0050	60C/90% R.H.	288 HRS	77	0
MOISTURE SOAK	0101	60C/90% R.H.	576 HRS	56	0
MOISTURE SOAK	0139	60C/90% R.H.	960 HRS	50	0
Total:					2

Assembly Information:

Assembly Site: Fastech
Pin Count: 36
Package Type: Module w/Hi Density SMT
Body Size: 720
Mold Compound: Amicon
Lead Frame: PCB; FR4
Lead Finsh:
Die Attach: ?
Bond Wire / Size: /
Flammability: UL 94-V0
Moisture Sensitivity
(JEDEC J-STD20A)
Date Code Range: 0139 to 0139

STORAGE LIFE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
STORAGE LIFE	0139	85 C	1000 HRS	77	0
Total:					0

TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
TEMP CYCLE	0139	-40 TO 85C	1000 CYS	76	0
Total:					0

UNBIASED MOISTURE RESISTANCE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
MOISTURE SOAK	0139	60C/90% R.H.	960 HRS	76	0
Total:					0

